

Recent Patents on Electrical & Electronic Engineering **Covering Letter**

Bentham Science Publishers

www.benthamscience.com/eeng

Ms. /	Ref.	No:	

This article will not proceed for publication until we have received a signed copy of this standard covering letter.

FILL IN THE FORM IN CAPITALS AND RETURN TO:

Director Publications Bentham Science Publishers Executive Suite Y-2 P.O. Box 7917, Saif Zone Sharjah, U.A.E.

Title of Manuscript:

Fax Nos: +215-3109757 (USA)

+ 971-6-5571134 (UAE) $E\text{-mail:}\ \underline{eeng@benthamscience.org}$

Fax:			
Геl:			
E-mail 2:		 	

Author(s): Type of Article: (i) Review: ____ (ii) Research: ____ (iii) Others (Letter, Clinical Trial Study, etc.): ____

(tick mark $\sqrt{}$ the appropriate box if relevant)

1-This is to confirm that:

* Financial contributions to the work being reported are clearly acknowledged below, as are any potential conflicts of interest. Please complete below section.

Acknowledgement of funding: Any conflict of interest:

- a) The manuscript submitted has been prepared according to the journal's "Aims & Scope" and 'Instructions for Authors', and checked for all possible inconsistencies and typographical errors.
- b) On submission of the manuscript, the authors agree not to withdraw the manuscript at any stage prior to publication.
 - The names and affiliations of four referees which Bentham Science Publishers (BSP in short) may decide to consult for the evaluation of the manuscript are listed below.

(Any suggested peer reviewers should not have published with any of the authors of the manuscript within the past five years and should not be members of the same research institution. Suggested reviewers will be considered alongside potential reviewers identified by their publication record or recommended by Editorial Board members).

Referee 1 Name: Address/Affiliation: Email:
Referee 2 Name: Address/Affiliation: Email:
Referee 3

Address/Affiliation:

Name:

Email:

Referee 4 Name: Address/ Email:	4 Affiliation:					
Eman.						
3-Bentha	am Open Access Plus (Optional)					
•	 Accepted articles can be published online for immediate free open access for all to view and download. Open access publishing provides a means for the maximum dissemination of the article to a larger audience. Authors can self-archive and post their articles on any digital repository of their choice. The fee for open access for authors is US\$ 890 					
•	I agree to pay the open access fee of US\$ 890 for an indefinite open access period for my article.					
	YES □ / NO □ (tick mark √ the appropriate box if relevant)					
4- Langu	nage and Editing (Optional)					
• Authors from non-native English speaking countries are requested to have the English language of their submitted manuscript checked, corrected and verified by a native English speaker. If you need any assistance in having the English grammar and style of your manuscript checked and improved, then please contact Eureka Science (http://www.eureka-science.com) at info@eureka-science.com), for a language editing quote.						
	• Do you need English-language support? YES \square / NO \square (tick mark $$ the appropriate box if relevant)					
Please no	ote that this service is not mandatory for submission of a manuscript to this journal.					
5- Copy	right and License Agreement					
For the s	ubmission of an 'article' to 'Recent Patents on Electrical & Electronic Engineering', I hereby certify that:					
1. I have	been granted authorization by my co-authors to enter into these arrangements.					
2. I hereb	by declare, on behalf of myself and my co-authors, that:					
a.	The article submitted is an original work and has neither been published in any other peer-reviewed journal nor is under consideration for publication by any other journal. More so, the work has been carried out in the authors' lab and the article does not contravene any existing copyright or any other third party rights.					
b.	I am/we are the sole author(s) of the article and maintain the authority to enter into this agreement and the granting of rights to <i>BSP</i> does not infringe any clause of this agreement.					
c.	The article contains no such material that may be unlawful, defamatory, or which would, if published, in any way whatsoever, violate the terms and conditions as laid down in the agreement.					
d.	d. I/we have taken due care that the scientific knowledge and all other statements contained in the article conform to true facts and authentic formulae and will not, if followed precisely, be detrimental to the user.					
e.	$I/we\ permit\ the\ adaptation,\ preparation\ of\ derivative\ works,\ or al\ presentation\ or\ distribution,\ along\ with\ the\ commercial\ application\ of\ the\ work.$					
f.	No responsibility is assumed by BSP , its staff or members of the editorial board for any injury and/or damage to persons or property as a matter of products liability, negligence or otherwise, or from any use or operation of any methods, products instruction, advertisements or ideas contained in a publication by BSP .					
Copyrig	ht:					
(a)	Authors who publish in any BSP print & online journal will transfer copyrights of their work to BSP. Submission of a manuscript implies that all authors have read and agreed to the content of this Covering Letter. It is a condition of publication that manuscripts submitted to this journal have not been published and will not be simultaneously submitted or published elsewhere. Plagiarism is strictly forbidden, and by submitting the article for publication the authors agree that the publishers have the legal right to take appropriate action against the authors, if plagiarism or fabricated information is discovered. By submitting a manuscript the authors agree that the copyright of their article is transferred to the publishers if and when the article is accepted for publication. Once submitted to the journal, the author will not withdraw their manuscript at any stage prior to publication.					
(b)	The/some figures included in the article are being reproduced with permission from the copyright holder.					
	YES \square / NO \square (tick mark $\sqrt{\ }$ the appropriate box if relevant)					
License	Grant:					
Ci-1						

Copyright to the above work (including without limitation, the right to publish the work in whole, or in part, in any and all forms) is hereby transferred to BSP, to ensure widest dissemination and protection against infringement. No proprietary right other than copyright is proclaimed by *BSP*.

Under the Following Conditions: Attribution:

- The services of the original author must be acknowledged;
- In case of reuse or distribution, the license conditions must be clarified to the user of this work;
- Any of these conditions can be ignored on the consent of the author.

CERTIFICATION AS A WORK OF	THE US GOVERNMENT							
I certify that this work is a "work of the US Government" prepared by the authors who are or were bona fide officers or employees of the US Government at the time of preparation of this document; therefore, it is not subject to US copyright. (This section should not be signed if the work was prepared under a government control or coauthored by a non-US Government employee).								
INDIVIDUAL AUTHOR OR AGENC	CY REPRESENTATIVE							
Print Authors' Name	Print Agency Representatives' Name and Title							
Original Signature of Author (in ink or electronic)	Original Signature of Agency Representative (in ink or electronic)	Date						
SIGN HERE FOR COPYRIGHT TRANSFER: I hereby certify that I am authorized to sign this document either in my own right or as a agent of my employer, and have made no changes to the current valid document supplied by <i>BSP</i> .								
Print Authorized Name(s) and Title(s)								
Original Signature(s) (in ink or elect	ronic) Date							

Please scan your signed copy of this covering letter and submit it along with your manuscript to the publisher.